

ABSTRACT

5 A method for fabricating semiconductor components and
interconnects includes the steps of providing a substrate,
such as a semiconductor die, forming external contacts on
opposing sides of the substrate by laser drilling vias
through the substrate, and forming conductive members in the
vias. The conductive members include enlarged terminal
10 portions that are covered with a non-oxidizing metal. The
method can be used to fabricate stackable semiconductor
packages having integrated circuits in electrical
communication with the external contacts. The method can
also be used to fabricate interconnects for electrically
15 engaging packages, dice and wafers for testing or for
constructing electronic assemblies.

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